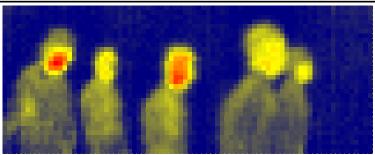


#### <Infrared Sensors>

# MIR8032B1

THERMAL DIODE INFRARED SENSOR, 80x32 pixels, FOV 78°x29°



#### DESCRIPTION

The MIR8032B1 is an infrared sensor array applying unique thermal diode technology. It has an SPI interface and comes together with an IR lens and an ASIC with an OTP\* memory that stores the sensitivity calibration data.

### **FEATURES**

• Pixel resolution: 80x32 pixels

FOV: 78° x 29°
 Flame rate: 4fps

NETD: 100mK (Typ.) @4fps

· Low height and light weight package

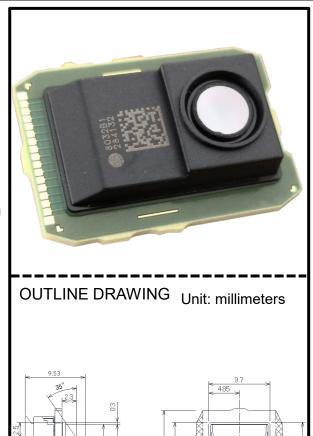
#### **APPLICATIONS**

 Security, Smart Building, People Counting, Temperature measurement, etc...

OTP\*: one time programmable

#### Absolute maximum ratings

Symbol	Parameter Min		Max	Unit
VDD	Power Supply Voltage	-0.3	3.8	>
MISO MOSI CLK NRST	Digital In-Out	-0.3	3.8	<b>V</b>
Tstg	Storage Temperature	-40	85	° C
Тор	Top Operation Temperature		85	° C



### **Electrical Characteristics**

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
ld	Current Consumption				50	mA
NETD	Noise Equivalent Temp. Difference	Vdd: 3.3V		100 @4fps		mK
FOVx	Field of View	Ta: 24° C		78		0
FOVy	Field of View			29		0

## **Main Revision for this Edition**

		Revision		
No.	Date	Pages	Points	
*	01/Apr./2020	*	New Release	
Α	17/Aug./2022	1	Corrected OUTLINE DRAWING.	

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